
sbRIO-9607

Specifications

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This document lists the specifications for the NI sbRIO-9607. The following specifications are typical for the -40 °C to +85 °C operating temperature range unless otherwise noted.



Caution Do not operate the sbRIO-9607 in a manner not specified in this document. Product misuse can result in a hazard. You can compromise the safety protection built into the product if the product is damaged in any way. If the product is damaged, return it to NI for repair.

Processor

| | |
|---------------------------------|--|
| Type | Xilinx Zynq-7000, XC7Z020 All Programmable SoC |
| Architecture | ARM Cortex-A9 |
| Speed | 667 MHz |
| Cores | 2 |
| Operating system | NI Linux Real-Time (32 bit) |
| Nonvolatile memory ¹ | 512 MB |
| Volatile memory (DRAM) | 512 MB |

1. Formatted nonvolatile memory may be slightly less than this value.

| | |
|-------------------------------------|----------------|
| Real-time clock, accuracy | 5 ppm |
| Flash reboot endurance ² | 100,000 cycles |



Note For information about the life span of the nonvolatile memory and about best practices for using nonvolatile memory, visit ni.com/info and enter the Info Code SSDBP.

Operating System



Note For minimum software support information, visit ni.com/info and enter the Info Code swsupport.

| | |
|--------------------------------------|---|
| Supported operating system | NI Linux Real-Time (32-bit) |
| Minimum software requirements | |
| Application software | |
| LabVIEW | LabVIEW 2015, LabVIEW 2015 Real-Time Module, LabVIEW 2015 FPGA Module |
| Driver software | NI CompactRIO Device Drivers August 2015 |

To set up a C/C++ based toolchain, visit ni.com/info and enter the info code NILRTCrossCompile for more information.

- You can increase the flash reboot endurance value by performing field maintenance on the device. If you expect that your application may exceed the maximum cycle count listed in this document, contact NI support for information about how to increase the reboot endurance value.

Reconfigurable FPGA

| | |
|--|--|
| Type | Xilinx Zynq-7000, XC7Z020 All Programmable SoC |
| Number of logic cells | 85,000 |
| Number of flip-flops | 106,400 |
| Number of 6-input LUTs | 53,200 |
| Number of DSP slices (18 x 25 multipliers) | 220 |
| Available block RAM | 560 KB |
| Number of DMA channels | 16 |
| Number of logical interrupts | 32 |

Network/Ethernet Port

| Number of interfaces | |
|----------------------|----------|
| Front Panel Ethernet | 1 (Eth0) |
| RMC Ethernet | 1 (Eth1) |

| | |
|--------------------------|---|
| Network interface | 10Base-T, 100Base-TX, and 1000Base-T Ethernet ³ |
| Compatibility | IEEE 802.3 |
| Communication rates | 10 Mbps, 100 Mbps, 1000 Mbps auto-negotiated, half-/full-duplex |
| Maximum cabling distance | 100 m/segment |

RS-232 (DTE) Serial Port

| | |
|-------------------------------|--|
| Number of interfaces | |
| Onboard RS-232 | 1 (Serial1) |
| RMC RS-232 via FPGA 3.3 V DIO | 4 (Serial2, Serial3, Serial4, Serial5) |
| Baud rate support | Arbitrary |
| Maximum baud rate | 230,400 bps |
| Data bits | 5, 6, 7, 8 |
| Stop bits | 1, 2 |

3. For revision C and earlier, 1000Base-T Ethernet link and communication is not guaranteed for primary or secondary Ethernet ports below -20 °C. If you expect ambient temperatures below -20 °C, NI recommends using a 10/100 network infrastructure or assigning 10/100Mbps communication speeds to the Ethernet Adapter in NI Measurement & Automation Explorer (MAX).

| | |
|--------------|----------------------------------|
| Parity | Odd, Even, Mark, Space |
| Flow control | RTS/CTS, XON/XOFF, DTR/DSR, None |

RS-485 Serial Port

| | |
|---|-----------------------------|
| Number of interfaces | |
| RMC RS-485 via FPGA 3.3 V DIO | 2 (Serial6, Serial7) |
| Maximum baud rate | 460,800 bps |
| Data bits | 5, 6, 7, 8 |
| Stop bits | 1, 1.5, 2 |
| Parity | Odd, Even, Mark, Space |
| Flow control | XON/XOFF |
| Wire mode | 4-wire, 2-wire, 2-wire auto |
| Isolation voltage, port to earth ground | None |

Embedded CAN

| |
|-----------------------------|
| Number of interfaces |
|-----------------------------|

| | |
|----------------------------|----------------|
| Onboard CAN | 1 (CAN0) |
| RMC CAN via FPGA 3.3 V DIO | 1 (CAN1) |
| Onboard CAN transceiver | NXP PCA82C251T |
| Maximum baud rate | 1 Mbps |
| Minimum baud rate | 10 kbps |

USB Port

| | |
|---------------------------------|-------------------|
| Number of interfaces | |
| Front Panel USB Host | 1 (USB0) |
| RMC USB Host/Device | 1 (USB1) |
| Compatibility | USB 2.0, Hi-Speed |
| Maximum data rate | 480 Mb/s |
| Maximum front panel USB current | 900 mA |

3.3 V Digital I/O on RMC Connector

| | |
|------------------------------------|------------|
| Number of DIO channels | 96 |
| Maximum tested current per channel | ± 3 mA |



Note The performance of the RMC DIO pins is bounded by the FPGA, signal integrity, the application timing requirements, and the RMC design. A general SPI application will typically be able to meet these requirements and achieve frequencies of up to 10 MHz. For more information on using DIO to connect to RMCs, visit ni.com/r/RMCDIO.

| Input logic levels | |
|--|-------------------------------|
| Input low voltage, V_{IL} | -0.3 V minimum; 0.8 V maximum |
| Input high voltage, V_{IH} | 2.0 V minimum; 3.45 V maximum |
| Output logic levels | |
| Output high voltage, V_{OH} when sourcing 3 mA | 2.4 V minimum; 3.45 V maximum |
| Output low voltage, V_{OL} when sinking 3 mA | 0.0 V minimum; 0.4 V maximum |

CMOS Battery



Note The battery is user-replaceable. The NI sbRIO device ships with a BR1225 coin cell battery from RAYOVAC, which is industrial-rated. Ensure that power remains connected to the NI sbRIO device while you replace the

battery so that time-keeping is not disrupted. Refer to the [Battery Replacement and Disposal](#) section for information about replacing the battery.

| | |
|--|------------------------|
| Typical battery life with power applied to power connector | 10 years |
| Typical battery life in storage at 55 °C | 2.5 years ⁴ |

Power Outputs on RMC



Caution Exceeding the power limits may cause unpredictable device behavior.

| | |
|--------------------------------|----------------|
| +5 V power output | |
| Output voltage | 5 V \pm 5% |
| Maximum current | 1.5 A |
| Maximum ripple and noise | 50 mV |
| +3.3 V_AUX power output | |
| Output voltage | 3.3 V \pm 5% |
| Maximum current | 0.33 A |
| Maximum ripple and noise | 50 mV |

4. Battery life may drop dramatically in extreme temperatures.

| FPGA_VIO power output | |
|--------------------------|----------------|
| Output voltage | 3.3 V \pm 5% |
| Maximum current | 0.33 A |
| Maximum ripple and noise | 50 mV |

Power Requirements

The NI sbRIO device requires a power supply connected either to the power connector or through the VIN_filtered pins through the RMC. Refer to the **Powering On the NI sbRIO Device** section in the **NI sbRIO-9607 Getting Started Guide** on ni.com/manuals for information about connecting the power supply. Refer to the **NI sbRIO-9607/9627 RMC Design Guide** on ni.com/manuals for more information about how to power the NI sbRIO device through the RMC.



Caution Exceeding the power limits may cause unpredictable device behavior.

| | |
|-----------------------------|----------------------|
| Recommended power supply | 55 W, 30 VDC maximum |
| Power supply voltage range | 9 VDC to 30 VDC |
| Reversed-voltage protection | 30 VDC |
| Power consumption with RMC | 28 W maximum |

Environmental



Caution Clean the sbRIO-9607 with a soft, nonmetallic brush. Make sure that the device is completely dry and free from contaminants before returning it to service.

| | |
|--|------------------------------|
| Local ambient operating temperature near device (IEC 60068-2-1, IEC 60068-2-2) | -40 °C to 85 °C ⁵ |
| Maximum reported onboard sensor temperature | |
| CPU/FPGA temperature | 98 °C |
| Primary System temperature | 85 °C |
| Secondary System temperature | 85 °C |

Table 1. Component Maximum Case Temperature

| Component | Manufacturer | Maximum Case Temperature |
|------------|--------------|--------------------------|
| CPU/FPGA | Xilinx | NA ⁶ |
| DDR memory | Micron | 95 °C |
| NAND flash | Micron | 89 °C |
| CPLD | Lattice | 94 °C |
| USB PHY | Microchip | 120 °C |
| ENET PHY | Micrel | 120 °C |

The sbRIO-9607 includes three onboard temperature monitoring sensors to simplify validation of a thermal solution by indicating thermal performance during validation

- If you expect ambient temperatures below -20 °C, NI recommends using a 10/100 network infrastructure or assigning 10/100Mbps communication speeds to the Ethernet Adapter in NI MAX. Refer to the [Network/Ethernet Port](#) section of this document for more information.
- Use digital approach to ensure the on-chip temperature reading is below 98°C.

and deployment. The sensors measure the CPU/FPGA junction temperature and printed circuit board temperatures that can be used to approximate the primary and secondary side local ambient temperatures. This approach is called digital validation. Alternatively, the traditional analog approach using thermocouples can be used to validate thermal performance. The digital approach is more accurate for determining the performance of the CPU/FPGA but is more conservative for determining the local ambient temperatures. NI recommends using digital validation.

For digital validation, ensure that the reported CPU/FPGA, reported Primary System, and reported Secondary System temperatures do not exceed any of the maximum temperatures listed in this document. Thermal validation is complete if the reported temperatures are within specifications. For more information about how to access the onboard sensors, visit ni.com/info and enter the Info Code `sbriosensors`. If the reported Primary System temperature or reported Secondary System temperature exceed the maximum temperatures listed in this document then analog validation may be used for further verification.

For analog validation, measure the local ambient temperature by placing thermocouples on both sides of the PCB, 5 mm (0.2 in.) from the board surface. Avoid placing thermocouples next to hot components such as the CPU/FPGA or near board edges, which can cause inaccurate temperature measurements. In addition to the local ambient temperature, the case temperature of the components should not exceed the recommended maximum case temperature.



Note Some systems may require a heat sink or air flow to remain within the maximum allowed temperature ranges. You can mount the Thermal Kit for NI sbRIO-9607/9627/9637 (153901-02) heat spreader on the NI sbRIO device.



Note The NI sbRIO device thermal performance is greatly influenced by several factors, including resource utilization, mounting, and adjacent power dissipation. These factors can substantially affect the achievable external ambient temperature at which the maximum local and reported temperatures are reached. NI recommends additional thermal design to remain within the maximum allowed temperature ranges. For information about and examples of environmental and design factors that can affect the thermal performance of NI sbRIO systems, visit ni.com/info and enter the Info

Code `sbriocooling`. For device-specific guidelines about enabling proper thermal design, refer to the **NI sbRIO-9607 User Manual** on ni.com/manuals.

| | |
|--|---------------------------------|
| Storage temperature (IEC 60068-2-1, IEC 60068-2-2) | -40 °C to 85 °C |
| Operating humidity (IEC 60068-2-78) | 10% RH to 90% RH, noncondensing |
| Storage humidity (IEC 60068-2-78) | 5% RH to 95% RH, noncondensing |
| Maximum altitude | 5,000 m |
| Pollution Degree (IEC 60664) | 2 |

The NI sbRIO device is intended for indoor use only.

Physical Characteristics

| | |
|--------|-----------------|
| Weight | 87 g (3.069 oz) |
|--------|-----------------|

Safety Voltages

Connect only voltages that are below these limits.

| | |
|--------------------------|--|
| V terminal to C terminal | 30 VDC maximum, Measurement Category I |
|--------------------------|--|

Environmental Management

NI is committed to designing and manufacturing products in an environmentally responsible manner. NI recognizes that eliminating certain hazardous substances from our products is beneficial to the environment and to NI customers.

For additional environmental information, refer to the ***Engineering a Healthy Planet*** web page at ni.com/environment. This page contains the environmental regulations and directives with which NI complies, as well as other environmental information not included in this document.

EU and UK Customers

-  **Waste Electrical and Electronic Equipment (WEEE)**—At the end of the product life cycle, all NI products must be disposed of according to local laws and regulations. For more information about how to recycle NI products in your region, visit ni.com/environment/weee.

Battery Replacement and Disposal

-  **Battery Directive**—This product contains a long-life coin cell battery. If you need to replace it, use the Return Material Authorization (RMA) process or contact an authorized NI service representative. For more information about compliance with the EU Battery Directive 2006/66/EC about Batteries and Accumulators and Waste Batteries and Accumulators, visit ni.com/environment/batterydirective.

电子信息产品污染控制管理办法（中国RoHS）

-  **中国RoHS**—NI符合中国电子信息产品中限制使用某些有害物质指令 (RoHS)。关于NI中国RoHS合规性信息，请登录 ni.com/environment/rohs_china。(For information about China RoHS compliance, go to ni.com/environment/rohs_china.)

NI Services

Visit ni.com/support to find support resources including documentation, downloads, and troubleshooting and application development self-help such as tutorials and

examples.

Visit ni.com/services to learn about NI service offerings such as calibration options, repair, and replacement.

Visit ni.com/register to register your NI product. Product registration facilitates technical support and ensures that you receive important information updates from NI.

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